

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

| Name | Execution Date |
|-------------------|----------------|
| Seng Guan Chow | 08/27/2007 |
| Heap Hoe Kuan | 08/27/2007 |
| Linda Pei Ee Chua | 08/27/2007 |

RECEIVING PARTY DATA

| | |
|-----------------|--------------------|
| Name: | STATS ChipPAC Ltd. |
| Street Address: | 5 Yishun Street 23 |
| City: | Singapore |
| State/Country: | SINGAPORE |
| Postal Code: | 768442 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 11850197 |

CORRESPONDENCE DATA

Fax Number: (408)738-0881
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: (408) 738-0592
Email: efiling@ishimarulaw.com
Correspondent Name: Mikio Ishimaru
Address Line 1: Ishimaru & Zahrt LLP
Address Line 2: 333 W. El Camino Real, Suite # 330
Address Line 4: Sunnyvale, CALIFORNIA 94087

ATTORNEY DOCKET NUMBER: 27-387

NAME OF SUBMITTER: Mikio Ishimaru

Total Attachments: 3
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PATENT

REEL: 019785 FRAME: 0221

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CH \$40.00 11850197

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGE-ON-PACKAGE SYSTEM WITH ANTI-MOLD FLASH FEATURE

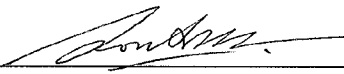
for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

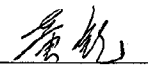
NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

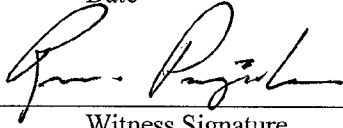
1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.


Seng Guan Chow

27 Aug. 2007
Date


Witness Signature


Witness Signature

HUANG RUI
Print Witness Name

REZA ARGENTY.
Print Witness Name

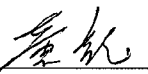
27 Aug 2007
Date

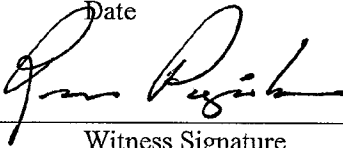
27 AUGUST '07
Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.


Heap Hoc Kuan

27 Aug 2007
Date


Witness Signature


Witness Signature

HUANG RUI
Print Witness Name

REZA ARGENTY.
Print Witness Name

27 Aug 2007
Date

27 AUGUST '07.
Date

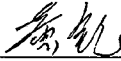
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



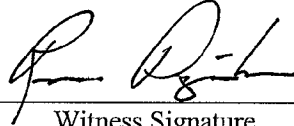
Linda Pei Ee Chua

27 Aug '07

Date



Witness Signature



Witness Signature

HUANG RUI

Print Witness Name

REZA ARGENTY.

Print Witness Name

27 Aug 2007

Date

27 AUGUST '07

Date